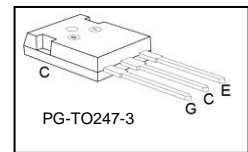
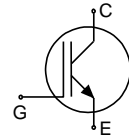


Low Loss IGBT : IGBT in TRENCHSTOP™ and Fieldstop technology



**Features:**

- Very low  $V_{CE(sat)}$  1.5V (typ.)
- Maximum Junction Temperature 175°C
- Short circuit withstand time 5μs
- Designed for :
  - Frequency Converters
  - Uninterruptible Power Supply
- TRENCHSTOP™ and Fieldstop technology for 600V applications offers :
  - very tight parameter distribution
  - high ruggedness, temperature stable behavior
  - very high switching speed
- Positive temperature coefficient in  $V_{CE(sat)}$
- Low EMI
- Low Gate Charge
- Qualified according to JEDEC<sup>1</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	$V_{CE}$	$I_C$	$V_{CE(sat), T_j=25^\circ C}$	$T_{j,max}$	Marking Code	Package
IGW30N60T	600V	30A	1.5V	175°C	G30T60	PG-TO247-3

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_j \geq 25^\circ C$	$V_{CE}$	600	V
DC collector current, limited by $T_{j,max}$ $T_C = 25^\circ C$ , value limited by bondwire $T_C = 100^\circ C$	$I_C$	45 39	A
Pulsed collector current, $t_p$ limited by $T_{j,max}$	$I_{C,puls}$	90	
Turn off safe operating area, $V_{CE} = 600V$ , $T_j = 175^\circ C$ , $t_p = 1\mu s$	-	90	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>2)</sup> $V_{GE} = 15V$ , $V_{CC} \leq 400V$ , $T_j \leq 150^\circ C$	$t_{SC}$	5	μs
Power dissipation $T_C = 25^\circ C$	$P_{tot}$	187	W
Operating junction temperature	$T_j$	-40...+175	
Storage temperature	$T_{stg}$	-55...+150	°C
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

<sup>1</sup> J-STD-020 and JESD-022

<sup>2)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

### Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		0.80	K/W
Thermal resistance, junction – ambient	$R_{thJA}$		40	

### Electrical Characteristic, at $T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.2mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=30A$ $T_j=25\text{ °C}$ $T_j=175\text{ °C}$	-	1.5	2.05	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.43mA,$ $V_{CE}=V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V,$ $V_{GE}=0V$ $T_j=25\text{ °C}$ $T_j=175\text{ °C}$	-	-	40	$\mu A$
			-	-	2000	
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=30A$	-	16.7	-	S
Integrated gate resistor	$R_{Gint}$		-			$\Omega$

### Dynamic Characteristic

Input capacitance	$C_{iss}$	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	1630	-	pF
Output capacitance	$C_{oss}$		-	108	-	
Reverse transfer capacitance	$C_{riss}$		-	50	-	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=30A$ $V_{GE}=15V$	-	167	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$	PG-TO-220-3-1 PG-TO-247-3-21	-	7 13	-	nH
Short circuit collector current <sup>1)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 5\mu s$ $V_{CC} = 400V,$ $T_j = 150\text{ °C}$	-	275	-	A

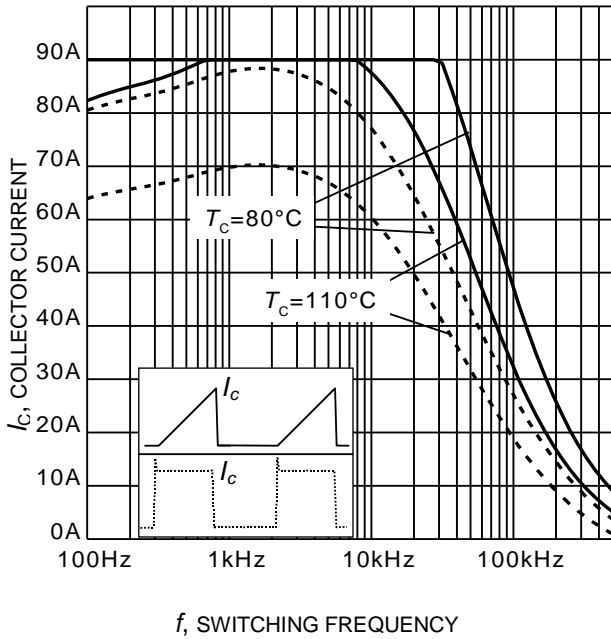
<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

### Switching Characteristic, Inductive Load, at $T_j=25\text{ °C}$

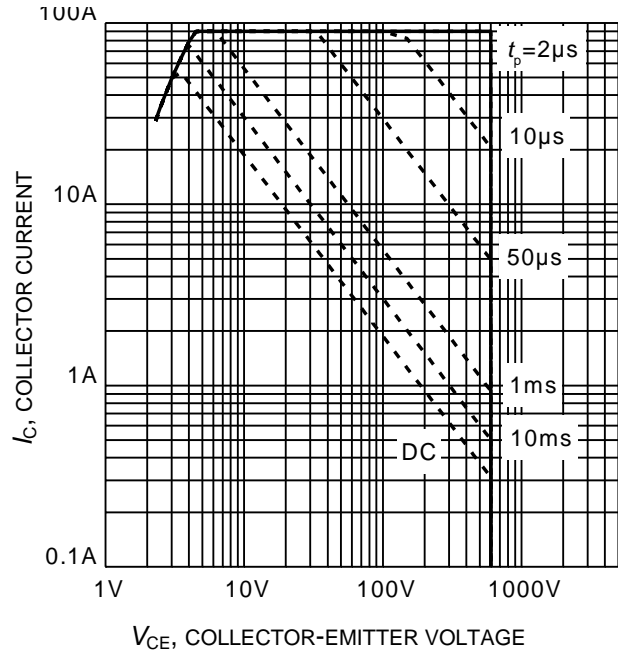
Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25\text{ °C}$ , $V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $V_{GE}=0/15\text{V}$ , $r_G=10.6\Omega$ , $L_\sigma=136\text{nH}$ , $C_\sigma=39\text{pF}$ $L_\sigma$ , $C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. Diode from IKW30N60T	-	23	-	ns
Rise time	$t_r$		-	21	-	
Turn-off delay time	$t_{d(off)}$		-	254	-	
Fall time	$t_f$		-	46	-	
Turn-on energy	$E_{on}$		-	0.69	-	mJ
Turn-off energy	$E_{off}$		-	0.77	-	
Total switching energy	$E_{ts}$		-	1.46	-	

### Switching Characteristic, Inductive Load, at $T_j=175\text{ °C}$

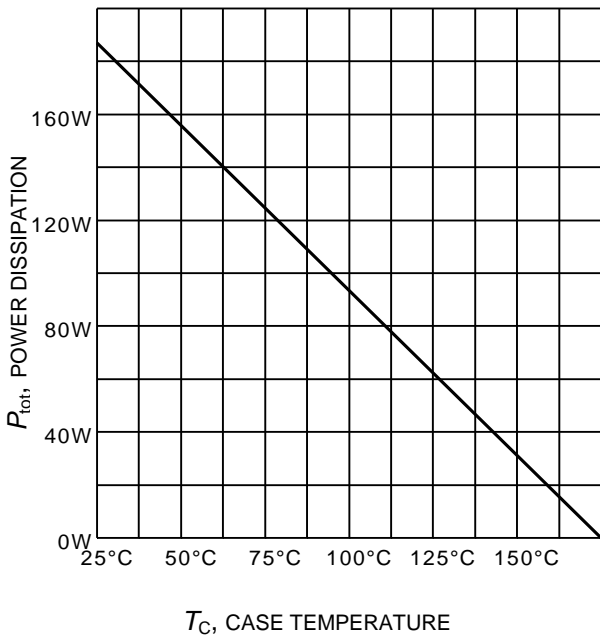
Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=175\text{ °C}$ , $V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $V_{GE}=0/15\text{V}$ , $r_G=10.6\Omega$ , $L_\sigma=136\text{nH}$ , $C_\sigma=39\text{pF}$ $L_\sigma$ , $C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. Diode from IKW30N60T	-	24	-	ns
Rise time	$t_r$		-	26	-	
Turn-off delay time	$t_{d(off)}$		-	292	-	
Fall time	$t_f$		-	90	-	
Turn-on energy	$E_{on}$		-	1.0	-	mJ
Turn-off energy	$E_{off}$		-	1.1	-	
Total switching energy	$E_{ts}$		-	2.1	-	



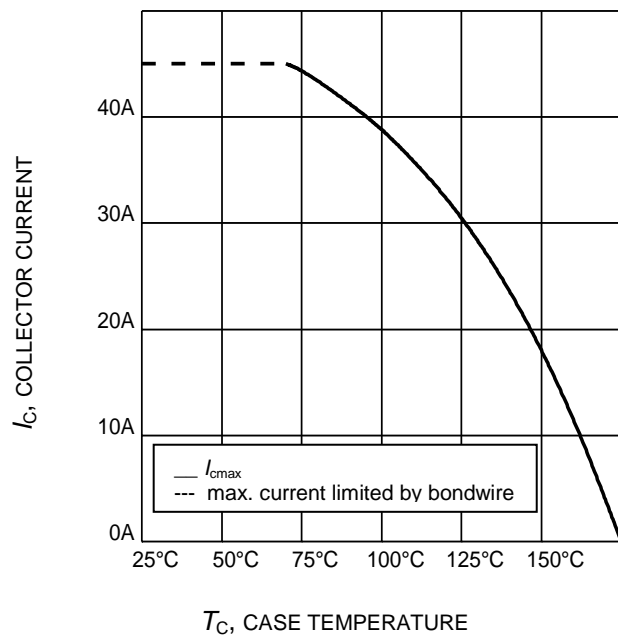
**Figure 1. Collector current as a function of switching frequency**  
 ( $T_j \leq 175^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 10\Omega$ )



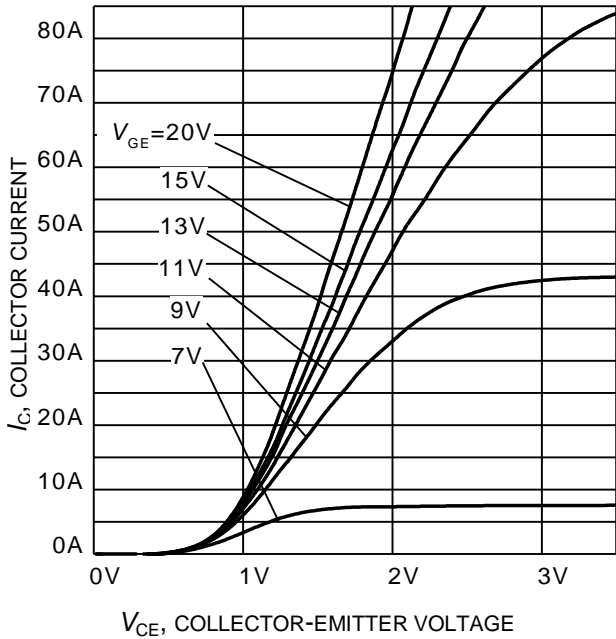
**Figure 2. Safe operating area**  
 ( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 175^\circ\text{C}$ ;  $V_{GE} = 0/15\text{V}$ )



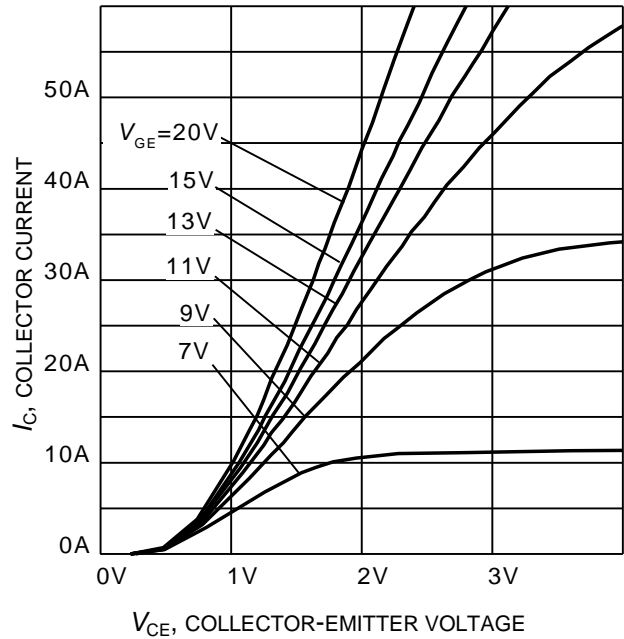
**Figure 3. Power dissipation as a function of case temperature**  
 ( $T_j \leq 175^\circ\text{C}$ )



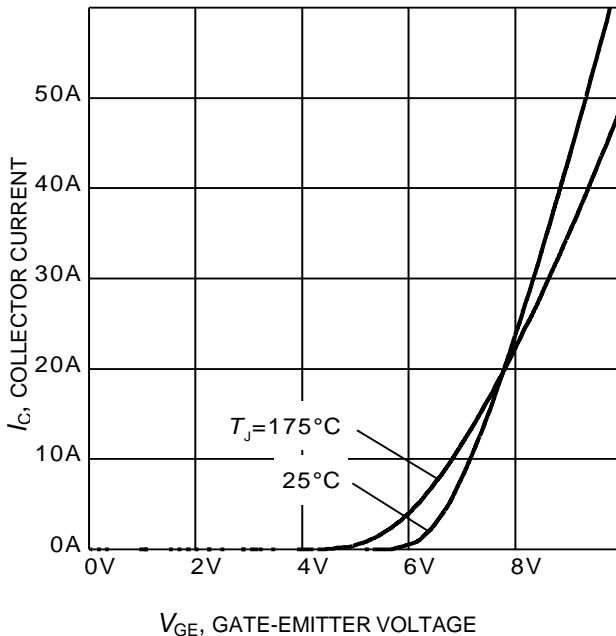
**Figure 4. Collector current as a function of case temperature**  
 ( $V_{GE} \geq 15\text{V}$ ,  $T_j \leq 175^\circ\text{C}$ )



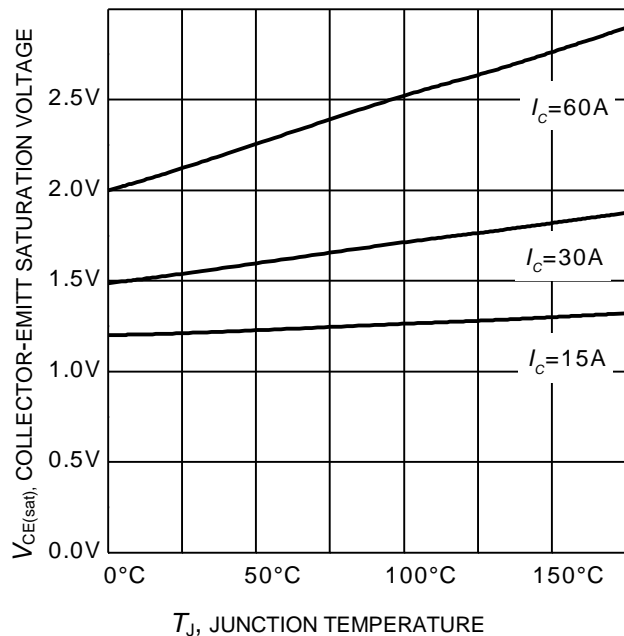
**Figure 5. Typical output characteristic**  
( $T_j = 25^\circ\text{C}$ )



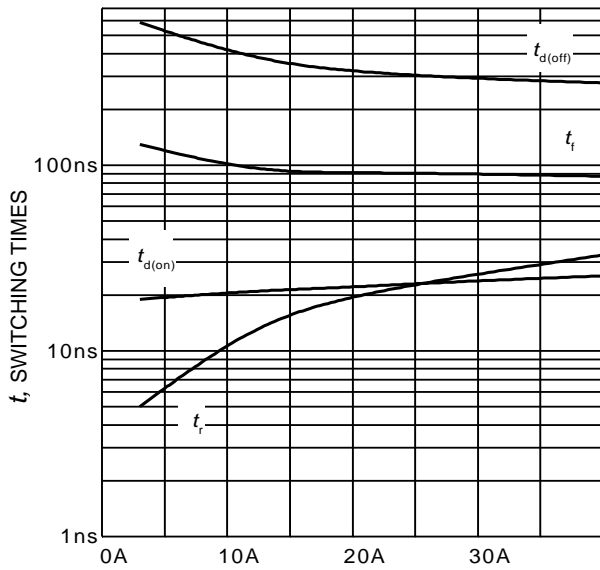
**Figure 6. Typical output characteristic**  
( $T_j = 175^\circ\text{C}$ )



**Figure 7. Typical transfer characteristic**  
( $V_{CE} = 20\text{V}$ )

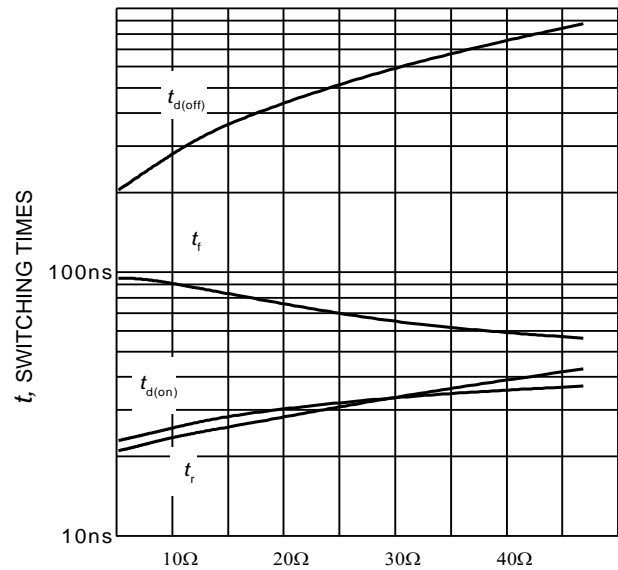


**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



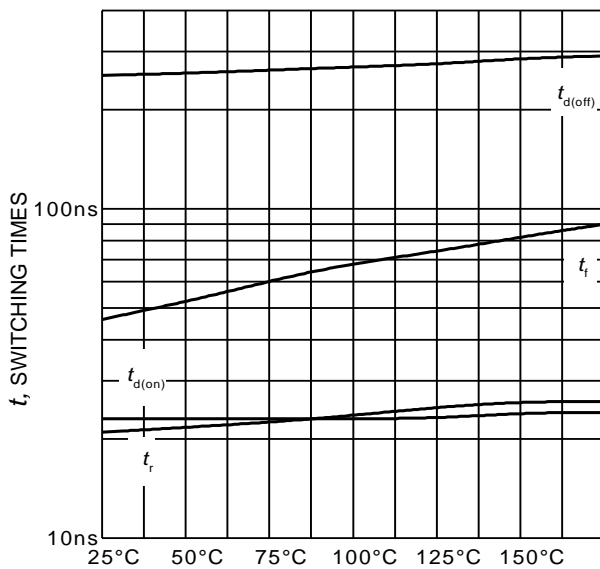
$I_C$ , COLLECTOR CURRENT

**Figure 9. Typical switching times as a function of collector current**  
(inductive load,  $T_J=175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 10\Omega$ ,  
Dynamic test circuit in Figure E)



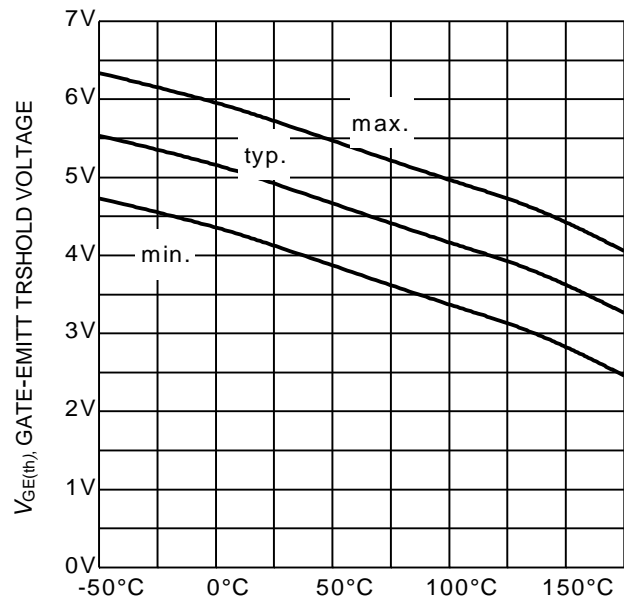
$R_G$ , GATE RESISTOR

**Figure 10. Typical switching times as a function of gate resistor**  
(inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 30\text{A}$ ,  
Dynamic test circuit in Figure E)



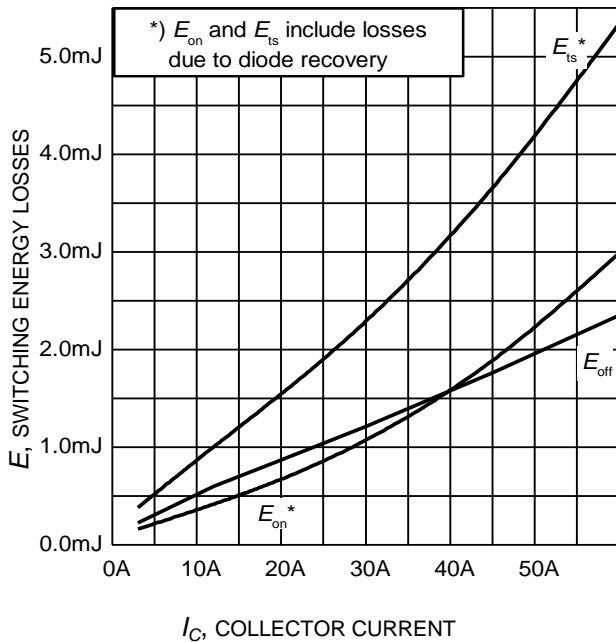
$T_J$ , JUNCTION TEMPERATURE

**Figure 11. Typical switching times as a function of junction temperature**  
(inductive load,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 30\text{A}$ ,  $r_G=10\Omega$ ,  
Dynamic test circuit in Figure E)

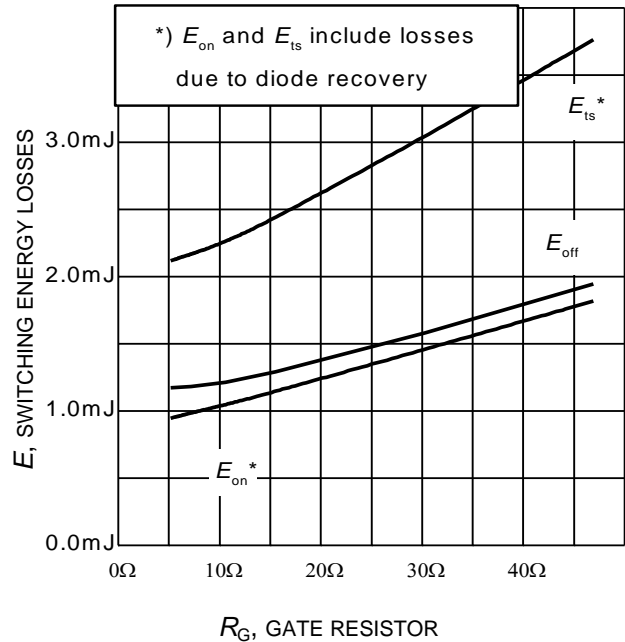


$T_J$ , JUNCTION TEMPERATURE

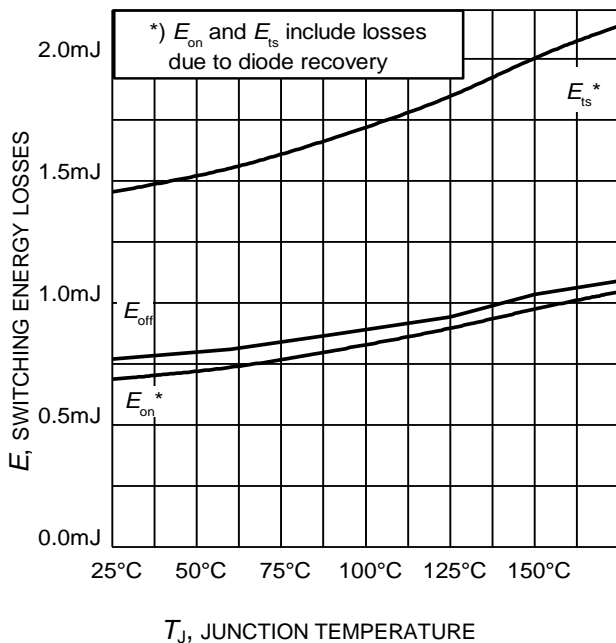
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
( $I_C = 0.43\text{mA}$ )



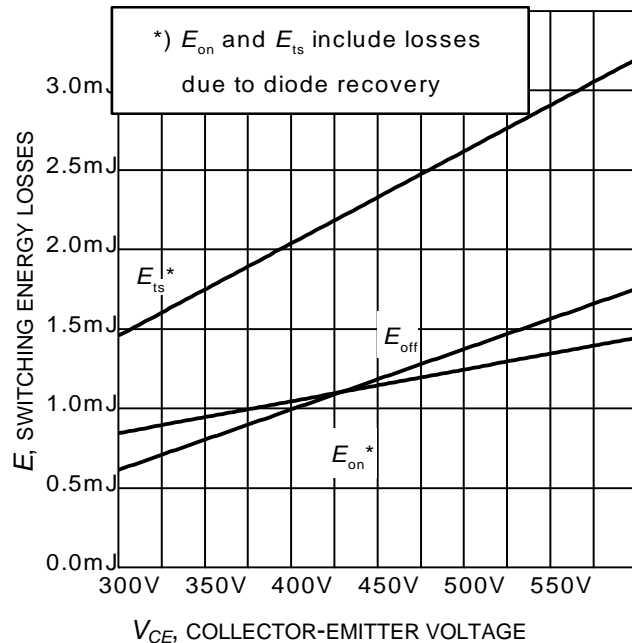
**Figure 13. Typical switching energy losses as a function of collector current**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 10\Omega$ , Dynamic test circuit in Figure E)



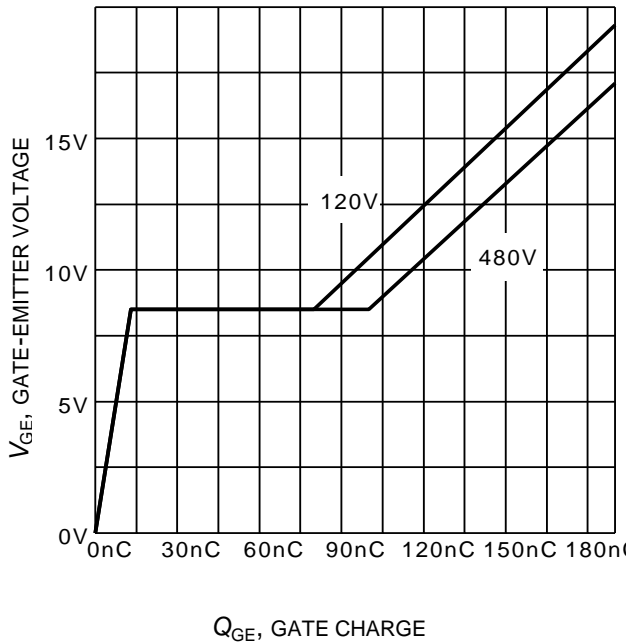
**Figure 14. Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 30\text{A}$ , Dynamic test circuit in Figure E)



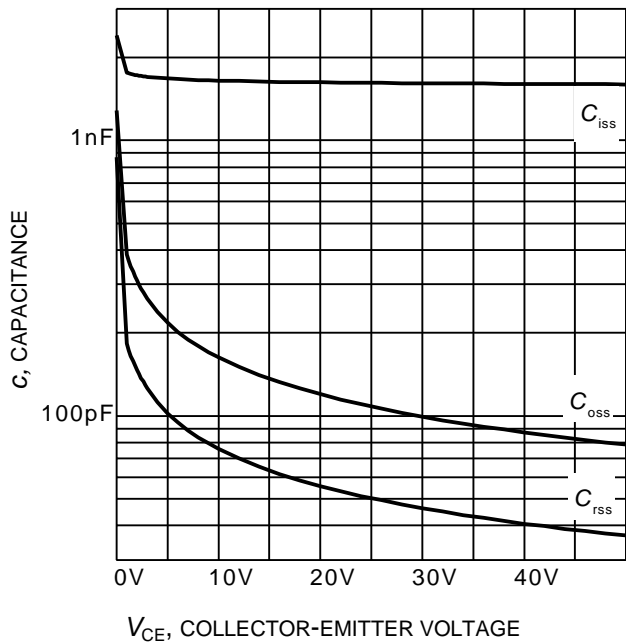
**Figure 15. Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 30\text{A}$ ,  $r_G = 10\Omega$ , Dynamic test circuit in Figure E)



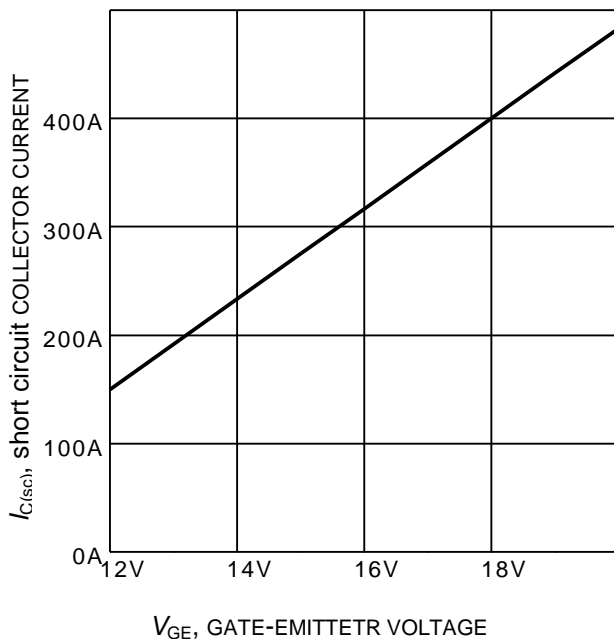
**Figure 16. Typical switching energy losses as a function of collector emitter voltage**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 30\text{A}$ ,  $r_G = 10\Omega$ , Dynamic test circuit in Figure E)



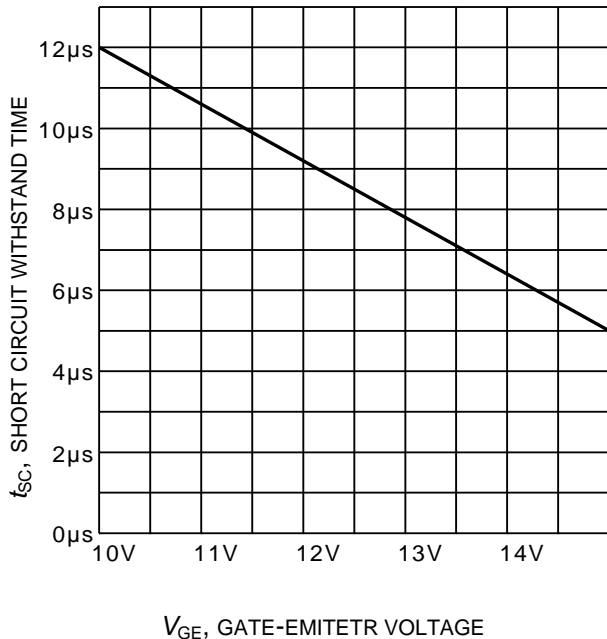
**Figure 17. Typical gate charge**  
( $I_C=30\text{ A}$ )



**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0\text{V}$ ,  $f = 1\text{ MHz}$ )

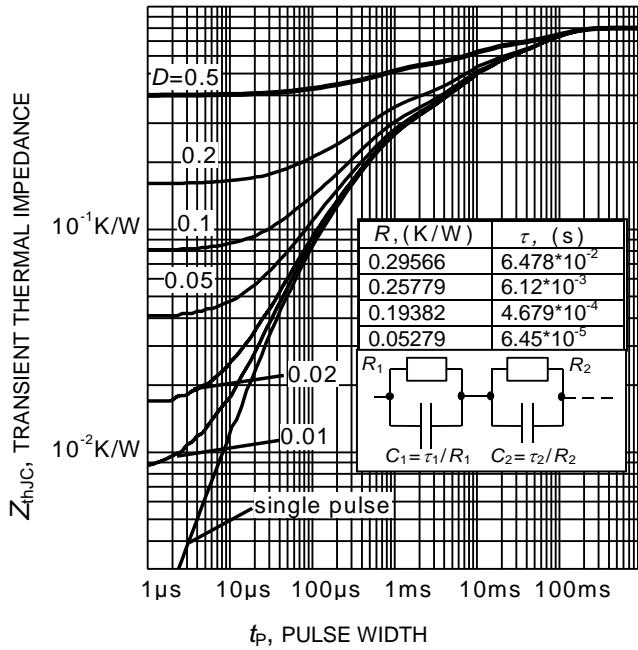


**Figure 19. Typical short circuit collector current as a function of gate-emittetr voltage**  
( $V_{CE} \leq 400\text{V}$ ,  $T_J \leq 150^\circ\text{C}$ )



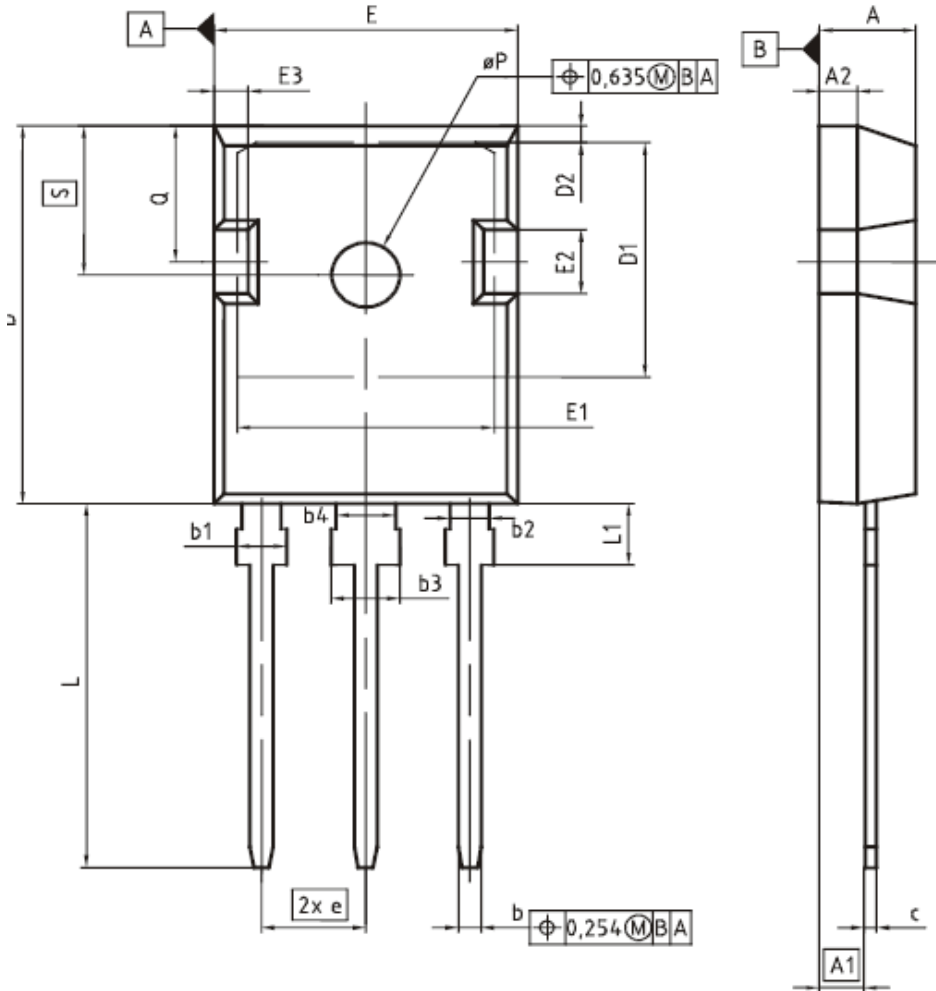
**Figure 20. Short circuit withstand time as a function of gate-emittetr voltage**  
( $V_{CE}=400\text{V}$ , start at  $T_J=25^\circ\text{C}$ ,  $T_{Jmax}<150^\circ\text{C}$ )





**Figure 21. IGBT transient thermal impedance**  
( $D = t_p / T$ )

### PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4,83	5,21	0,190	0,205
A1	2,27	2,54	0,089	0,100
A2	1,85	2,16	0,073	0,085
b	1,07	1,33	0,042	0,052
b1	1,90	2,41	0,075	0,095
b2	1,90	2,16	0,075	0,085
b3	2,87	3,38	0,113	0,133
b4	2,87	3,13	0,113	0,123
c	0,55	0,88	0,022	0,027
D	20,80	21,10	0,819	0,831
D1	16,25	17,85	0,640	0,695
D2	0,95	1,35	0,037	0,053
E	15,70	16,13	0,618	0,635
E1	13,10	14,15	0,516	0,557
E2	3,68	5,10	0,145	0,201
E3	1,00	2,60	0,039	0,102
e	5,44 (BSC)		0,214 (BSC)	
N	3		3	
L	19,80	20,32	0,780	0,800
L1	4,10	4,47	0,161	0,176
øP	3,50	3,70	0,138	0,146
Q	5,49	6,00	0,216	0,236
S	6,04	6,30	0,238	0,248

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**SCALE**

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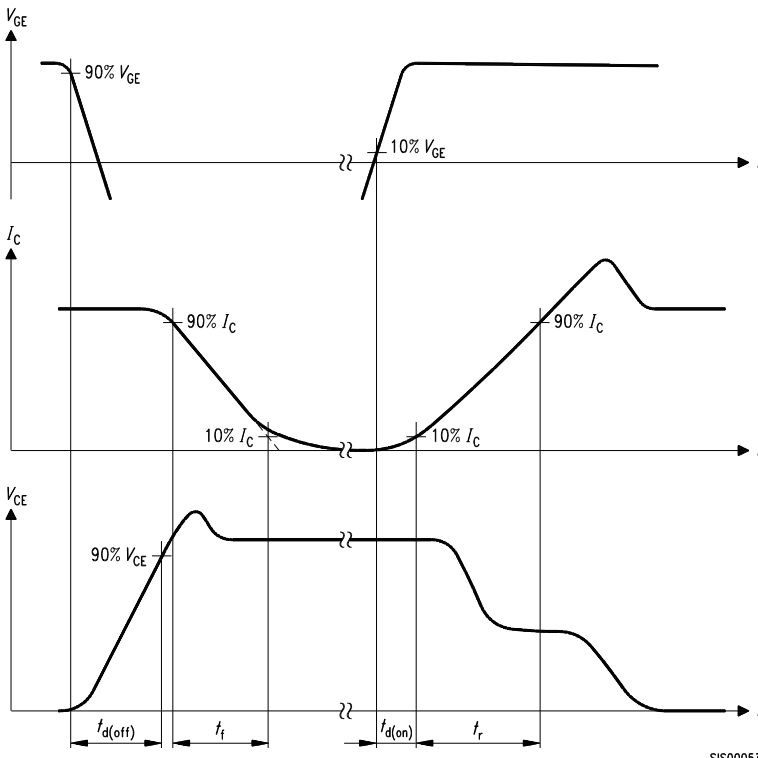


Figure A. Definition of switching times

SIS00053

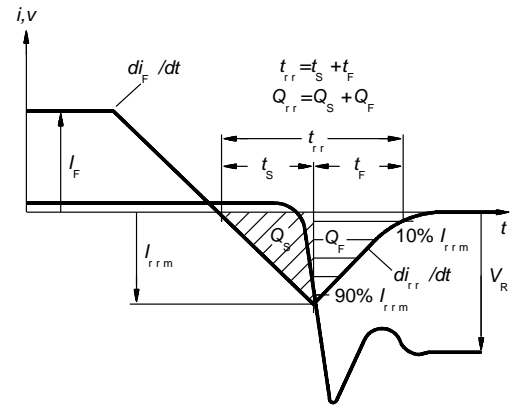


Figure C. Definition of diodes switching characteristics

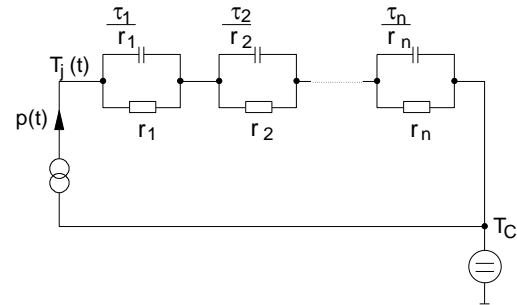


Figure D. Thermal equivalent circuit

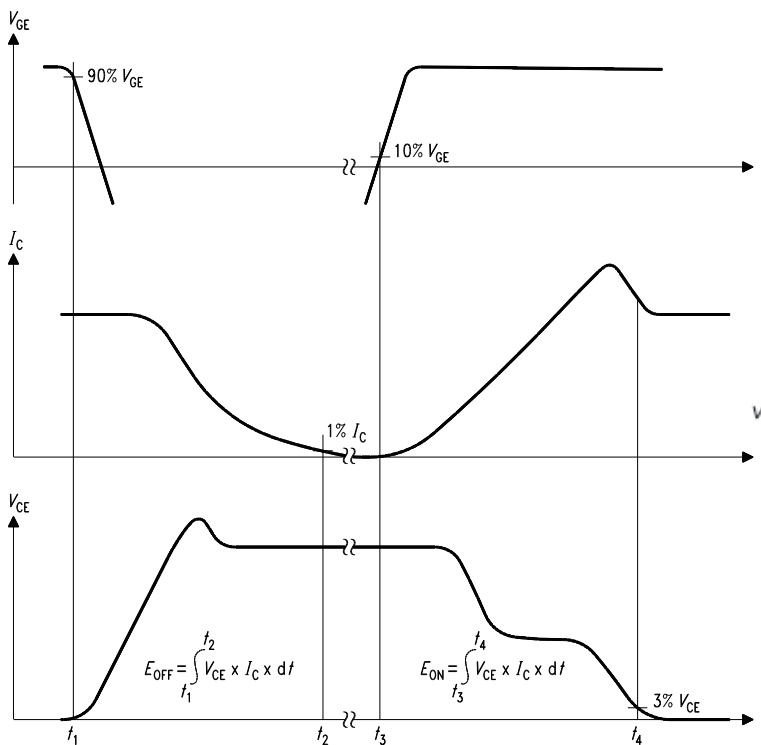


Figure B. Definition of switching losses

SIS00050

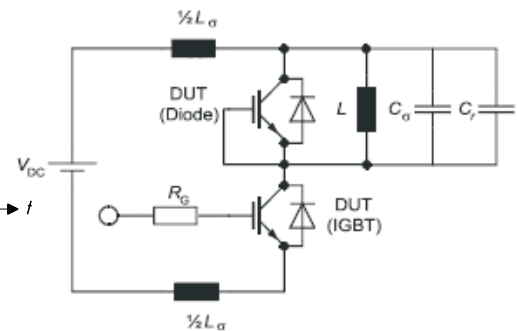


Figure E. Dynamic test circuit  
Parasitic inductance  $L_\sigma$ ,  
Parasitic capacitor  $C_\sigma$ ,  
Relief capacitor  $C_r$   
(only for ZVT switching)

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